

BF 4532 Series

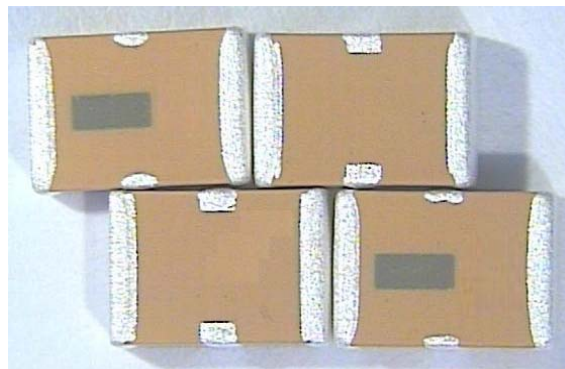
Multilayer Chip Band-Pass Filters

Features

- ❖ Ultra small SMD type with low loss at pass-band and high attenuation at stop-band.
- ❖ RoHS compliant.

Applications

- ❖ Wireless communication systems



Specifications

Part Number	Freq. Range (MHz)	Impedance (Ohm)	Insertion Loss @ BW (dB)	VSWR @ BW	Frequency (MHz)	Attenuation (dB)
BF4532-L1R5ACG_	1475 ~ 1675	75	3.0max.	2.0 max.	5 ~ 1350	30 min.
					2300 ~ 3000	30 min.

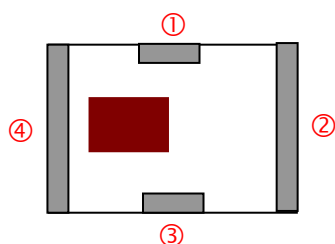
Q'ty/Reel (pcs) : 1000
 Operating Temperature Range : -40 ~ +85 °C
 Storage Temperature Range : -40 ~ +85 °C
 Storage Period : 12 months max.
 Power Capacity : 3W max.

Part Number

BF **4532** - **L** **1R5** **ACG** **□** **/LF**
 ① ② ③ ④ ⑤ ⑥ ⑦

① Type	BF : Band-Pass Filter	② Dimensions (L x W)	4.5 x 3.2 mm
③ Material Code	L	④ Frequency Range	1R5=1500MHz
⑤ Specification Code	ACG	⑥ Packaging	T: Tape & Reel B: Bulk
⑦ Soldering	/LF=lead-free		

Terminal Configuration

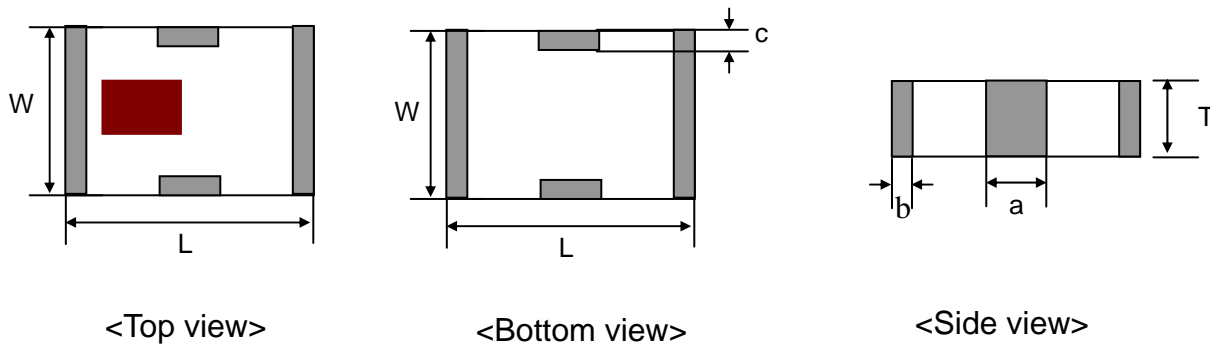


<Top view>

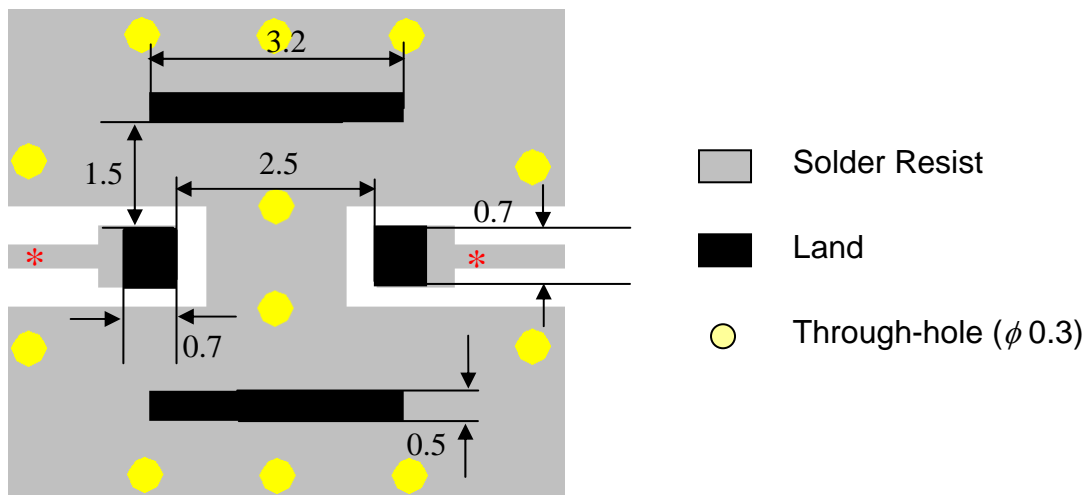
No.	Terminal Name	No.	Terminal Name
①	IN	③	OUT
②	GND	④	GND

Dimensions and Recommended PC Board Pattern

Unit: mm

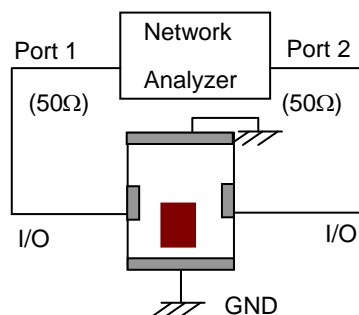


Mark	L	W	T	a	b	c
Dimensions	4.5 ±	3.2 ±	1.5 ±	0.7 ±	0.4 ±	0.35 ±
	0.2	0.2	0.1	0.1	0.1	0.1

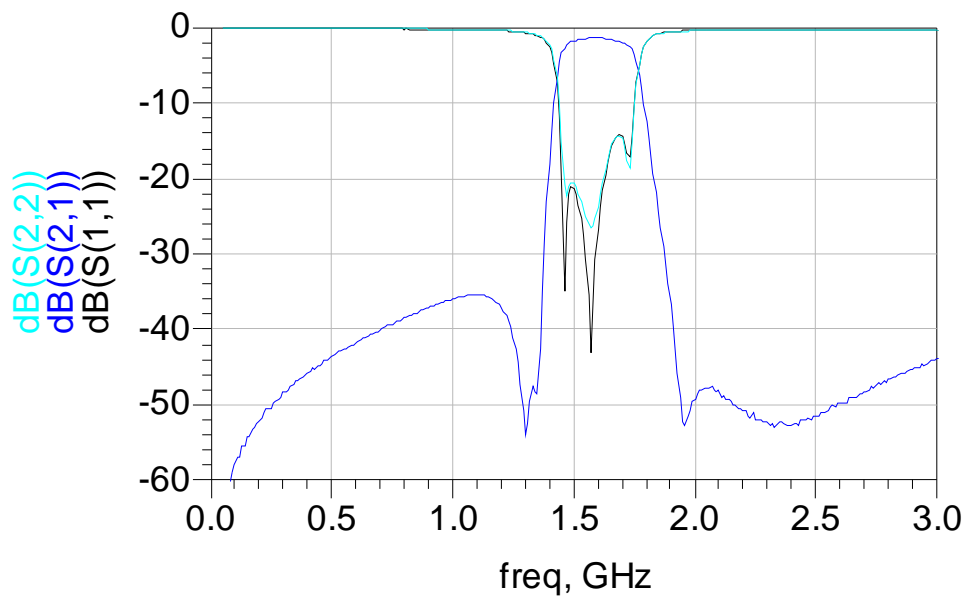


* Line width should be designed to match 50Ω characteristic impedance, depending on PCB material and thickness.

Measuring Diagram



Electrical Characteristics (T=25°C)

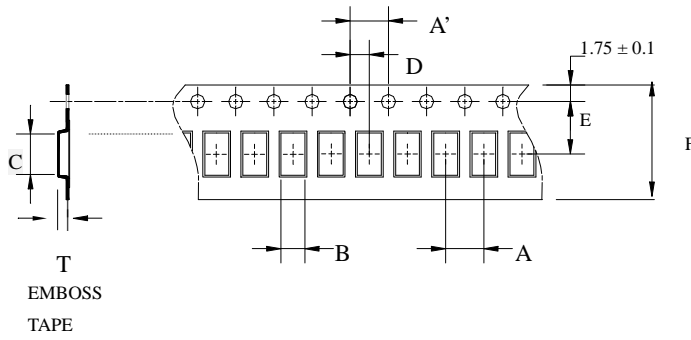


Notes

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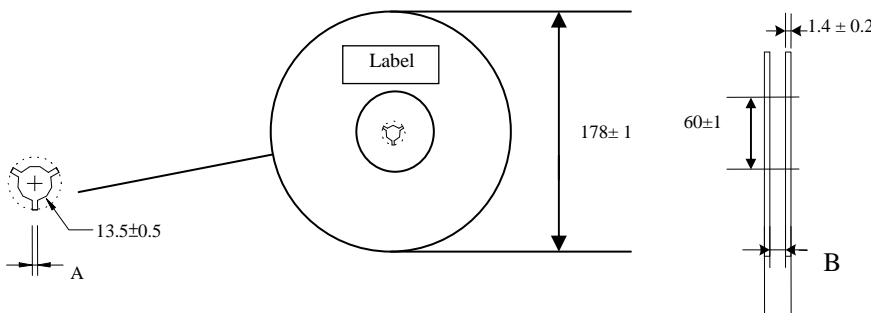
Taping Specifications

❖Tape & Reel Dimensions (Unit: mm) vs. Quantity (pcs)



Type	A	A'	B	C	D	E	F	T	Quantity/per reel	Tape material
4532	8.0± 0.1	4.0± 0.1	3.66± 0.1	4.95± 0.1	2.0± 0.1	5.5± 0.1	12.0± 0.1	1.75± 0.10	1,000pcs	Plastic (Embossed)

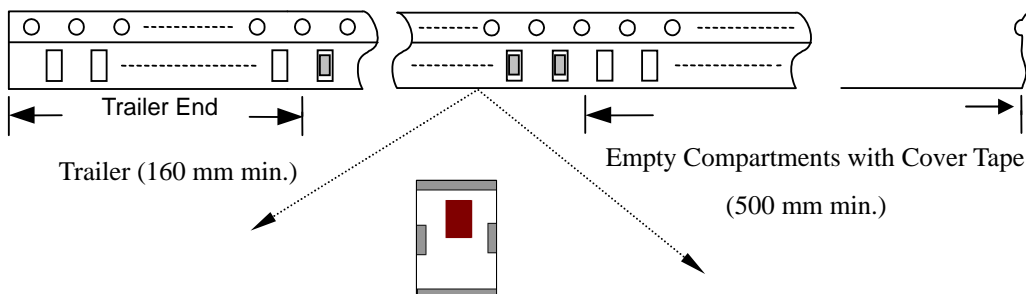
❖Reel Dimensions (Unit: mm)



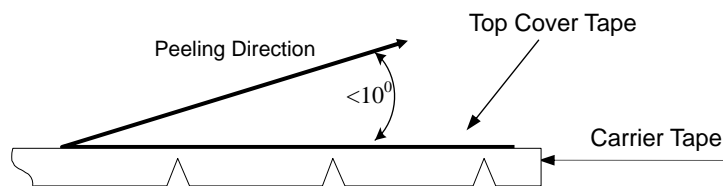
Label: Customer's Name,
ACX P/N, Q'ty, Date,
ACX Corp.

Type	A	B
4532	2.3±0.5	17.0±0.5

❖Leader and Trailer Tape



❖ **Peel-off Force**



Peel-off force should be in the range of 0.1 – 0.6 N at a peel-off speed of 300 ± 10 mm/min .

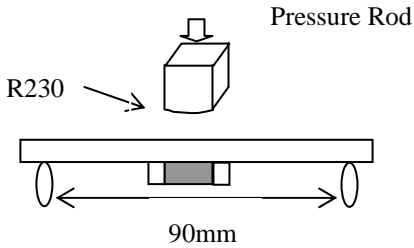
❖ **Storage Conditions**

- (1) Temperature: 5 ~35°C, relative humidity (RH): 45~75%.
- (2) Non-corrosive environment

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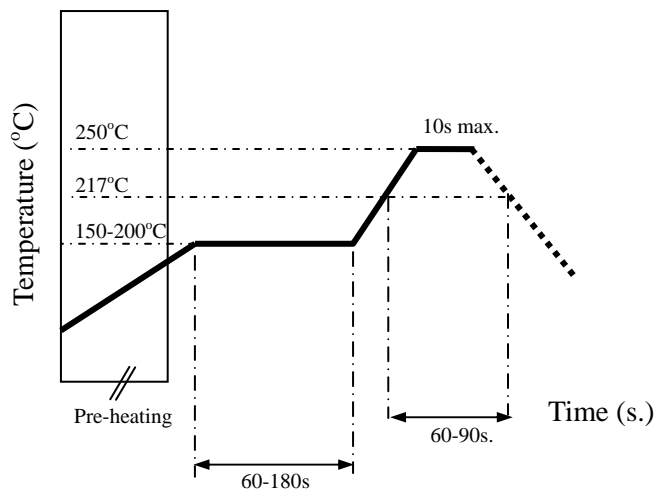
Mechanical & Environmental Characteristics

Item	Requirements	Procedure
Solderability	<ol style="list-style-type: none"> No apparent damage More than 75% of the terminal electrode shall be covered with new solder. 	<ol style="list-style-type: none"> Preheat: $120 \pm 5^\circ\text{C}$ Solder: $245 \pm 5^\circ\text{C}$ for 5 ± 1 sec
Soldering strength (Termination Adhesion)	<ol style="list-style-type: none"> 10N minimum 	<ol style="list-style-type: none"> Solder specimen onto test jig. Apply push force at 0.5mm/s until electrode pads are peeled off or ceramic are broken. Pushing force is applied to longitude direction
Deflection (Substrate Bending)	<ol style="list-style-type: none"> No apparent damage Fulfill the electrical specification 	<ol style="list-style-type: none"> Solder specimen onto test jig (FR4, 0.8mm) using the recommend soldering profile. Apply a bending force of 1mm deflection. 
Heat/Humidity Resistance	<ol style="list-style-type: none"> No apparent damage Fulfill the electrical specification after test 	<ol style="list-style-type: none"> Temperature: $85 \pm 2^\circ\text{C}$ Humidity: 90% ~ 95% RH Duration: 1000 ± 48hrs Recovery: 1-2hrs
Thermal shock (Temperature Cycle)	<ol style="list-style-type: none"> No apparent damage Fulfill the electrical specification after test 	<ol style="list-style-type: none"> One cycle/step 1 : $125 \pm 5^\circ\text{C}$ for 30 min step 2 : $-40 \pm 5^\circ\text{C}$ for 30 min No of cycles : 100 Recovery: 1-2 hrs
Low Temperature Resistance	<ol style="list-style-type: none"> No apparent damage Fulfill the electrical specification after test 	<ol style="list-style-type: none"> Temperature: $-40 \pm 5^\circ\text{C}$ Duration: 500 ± 24hrs Recovery: 1-2hrs

Soldering Conditions

❖ Typical Soldering Profile for Lead-free Process

Reflow Soldering



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